

# SOT523-1

plastic DIL-bent-SIL power package; 9 leads (lead length 12/11 mm); exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	DBS9P
<b>Package type industry code</b>	DBS9P
<b>Package style descriptive code</b>	DBS (DIL-bent-SIL)
<b>Package style suffix code</b>	P (power)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

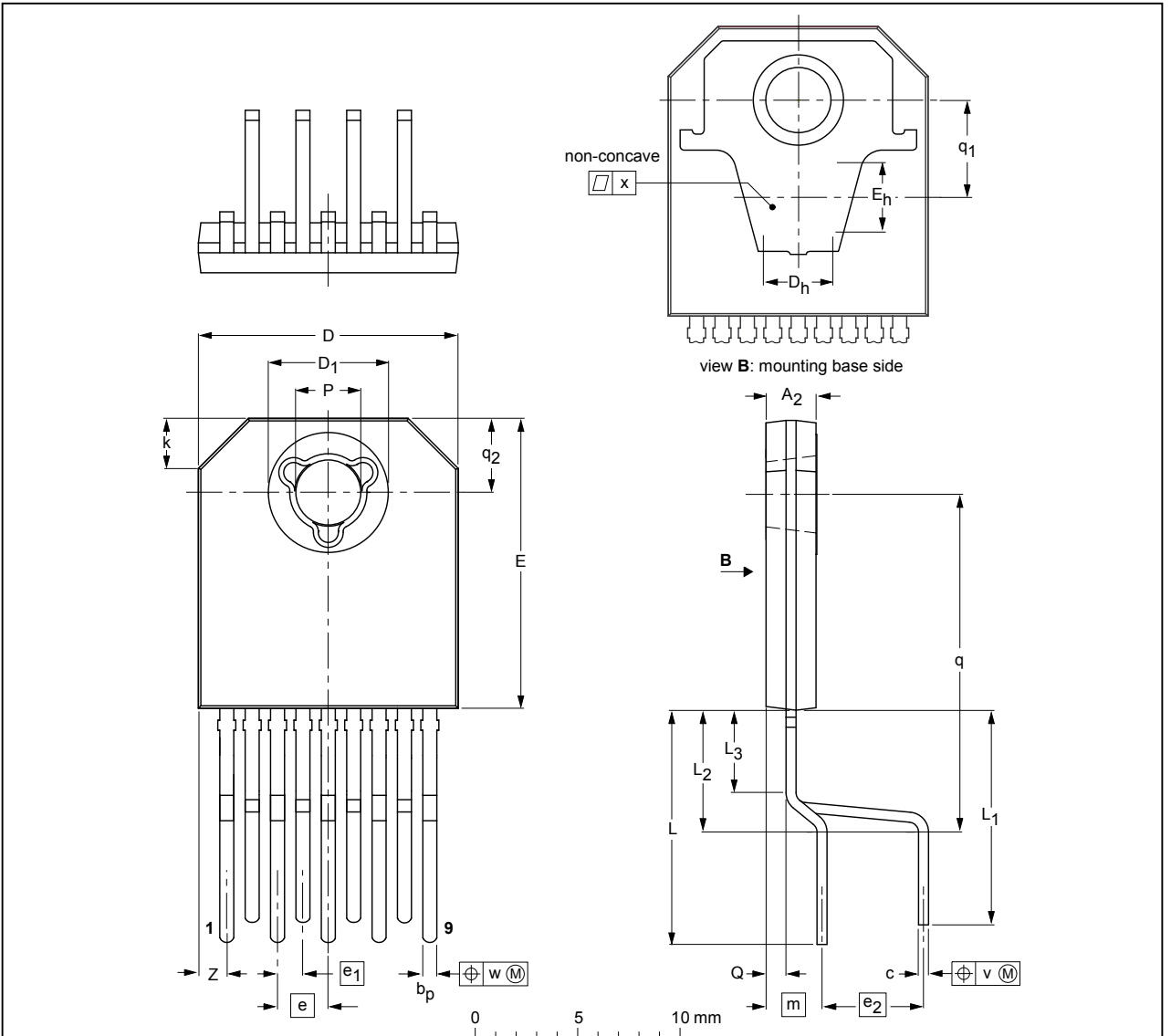
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.8	-	13	13.2	mm
E	package width	14.3	-	14.5	14.7	mm
A <sub>2</sub>	package height	2.3	-	2.5	2.7	mm
n <sub>2</sub>	actual quantity of termination	-	-	9	-	



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2. Package outline

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>2</sub> <sup>(2)</sup>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>1</sub> <sup>(2)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	k	L	L <sub>1</sub>	L <sub>2</sub>	L <sub>3</sub>	m	P	Q	q	q <sub>1</sub>	q <sub>2</sub>	v	w	x	Z <sup>(1)</sup>
mm	2.7	0.80	0.58	13.2	6.2	3.5	14.7	3.5	2.54	1.27	5.08	3	12.4	11.4	6.7	4.5	2.8	3.4	1.15	17.5	4.85	3.8	0.8	0.3	0.02	1.65
	2.3	0.65	0.48	12.8	5.8		14.3					2	11.0	10.0	5.5	3.7		3.1	0.85	16.3	3.6					1.10

- Notes
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.
  2. Plastic surface within circle area D<sub>1</sub> may protrude 0.04 mm maximum.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT523-1					-00-07-03- 03-03-12

Fig. 1. Package outline DBS9P (SOT523-1)

### 3. Legal information

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